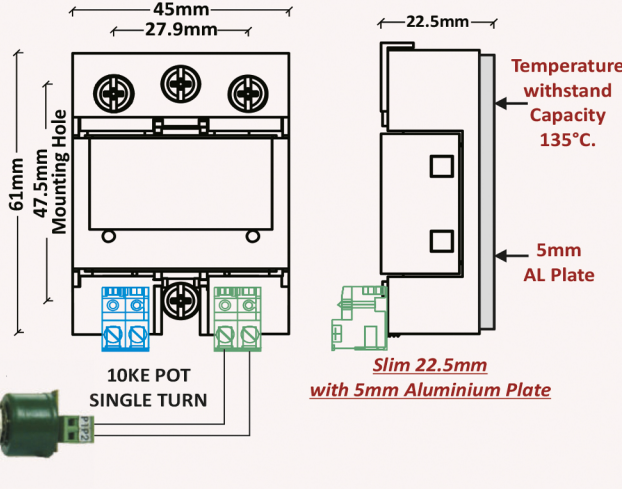
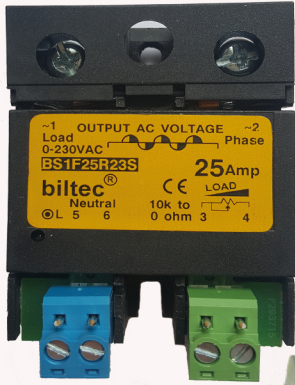




ISO 9001:2015 & ISO 14001:2015 CERTIFIED by InterConformity GmbH

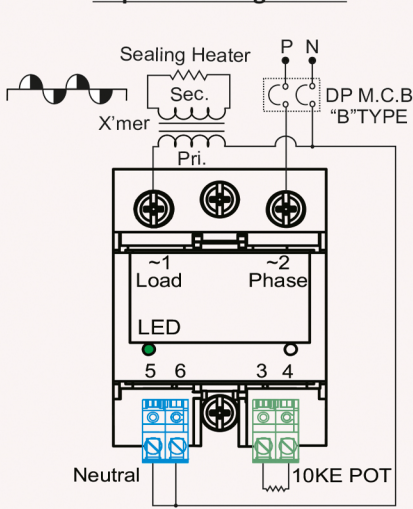
BS1F..R



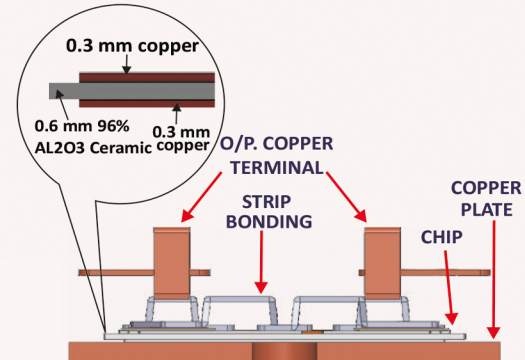
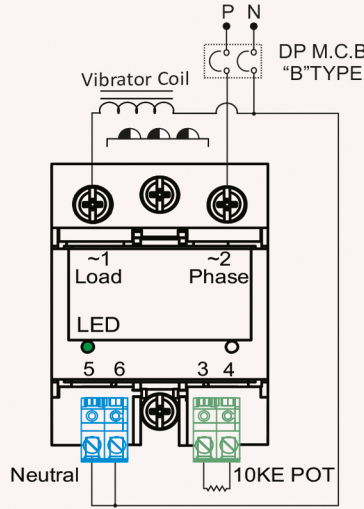
Phase Angle Control by POT with Neutral

- Product Temperature withstand 150°C.
- "22.5 MM SLIM Height" SSM Design.
- With easy open & lock IP 20 protection Flaps on O/P Terminals.
- Rating from 25 Amp, 50 Amp & 90 Amp @25°C 230VAC/440VAC.
- Short Circuit Protected SSM up to 63 Amp per phase current by help of suitable "B" curve MCB.
- No need to use semiconductor Fuse due to short circuit protected SSM.
- Fire Retardant Plastic as per UL94 VO GRADE.
- New improved SEMS Screw - Washers Output terminals.
- Improved Direct Bonded Copper (DBC) for higher Amp MODULES.
- High resistance to aggressive chemicals and dust due to special Potting.
- Logic compatibility, Fast switching, Low coupling capacitance.
- Inbuilt transient voltage suppressor.

FULL CONTROL Impulse Sealing Heater



HALF CONTROL Vibration Transformer without diode



Direct Copper Bonded (DCB) or Direct Bonded Copper (DBC) improves the conduction of heat from semiconductor chip to external heat sink as well as reduces mechanical stress in connection to major load changes. Here two layers of 0.3 mm copper is bonded to ceramic at temperature above 1020 °C. Coefficient of thermal expansion of copper is higher than ceramic (96% AL203) so a joint layer is generated between them at high temperature which will not cause thermal stress or fatigue on power output semiconductors.